

SANYO Semiconductors

DATA SHEET

2SK1461 — General-Purpose Switching Device Applications

Features

- Low ON-state resistance.
- Ultrahigh-speed switching.

Specifications

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		900	V
Gate-to-Source Voltage	VGSS		±30	V
Drain Current (DC)	۱D		5	А
Drain Current (Pulse)	IDP	PW≤10μs, duty cycle≤1%	10	А
Allowable Power Dissipation	De		2.5	W
	PD	Tc=25°C	120	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	Unit
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	900			V
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =900V, V _{GS} =0V			1.0	mA
Gate-to-Source Leakage Current	IGSS	$V_{GS}=\pm 30V, V_{DS}=0V$			±100	nA
Cutoff Voltage	VGS(off)	VDS=10V, ID=1mA	2.0		3.0	V
Forward Transfer Admittance	yfs	V _{DS} =20V, I _D =2A	1.0	2.0		S
Static Drain-to-Source On-State Resistance	R _{DS} (on)	ID=2A, VGS=10V		2.8	3.6	Ω

(Note) Be careful in handling the 2SK1461 because it has no protection diode between gate and source.

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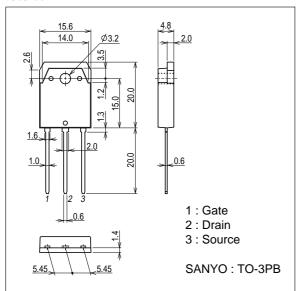
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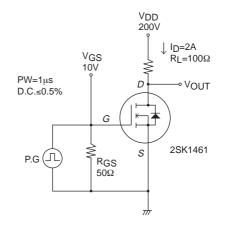
Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	Unit
Input Capacitance	Ciss	VDS=20V, f=1MHz		700		pF
Output Capacitance	Coss	V _{DS} =20V, f=1MHz		300		pF
Reverse Transfer Capacitance	Crss	V _{DS} =20V, f=1MHz		170		pF
Turn-ON Delay Time	t _d (on)	ID=2A, VGS=10V, VDD=200V, RGS=50Ω		15		ns
Rise Time	tr	ID=2A, VGS=10V, VDD=200V, RGS=50Ω		35		ns
Turn-OFF Delay Time	t _d (off)	ID=2A, VGS=10V, VDD=200V, RGS=50Ω		200		ns
Fall Time	tf	ID=2A, VGS=10V, VDD=200V, RGS=50Ω		65		ns
Diode Forward Voltage	V _{SD}	IS=5A, VGS=0V			1.8	V

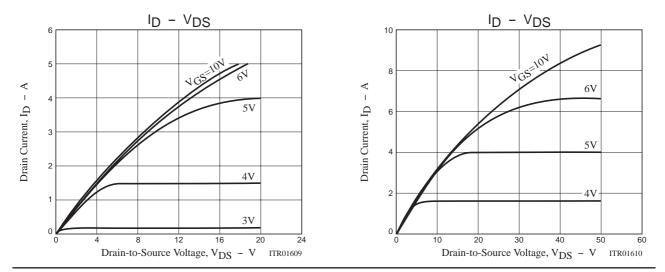
Package Dimensions

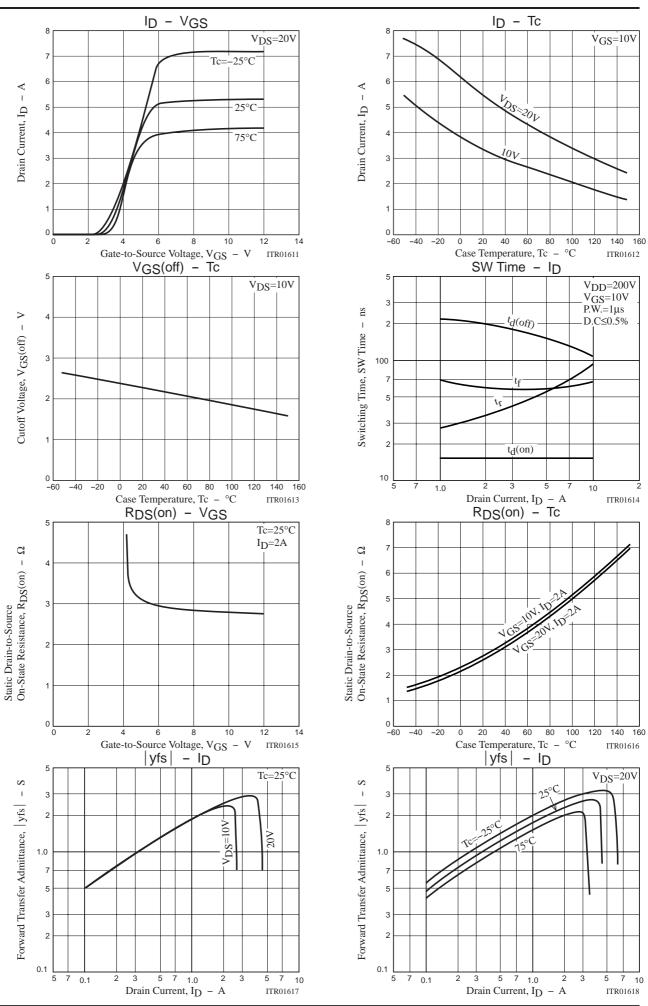
unit : mm (typ) 7503-004

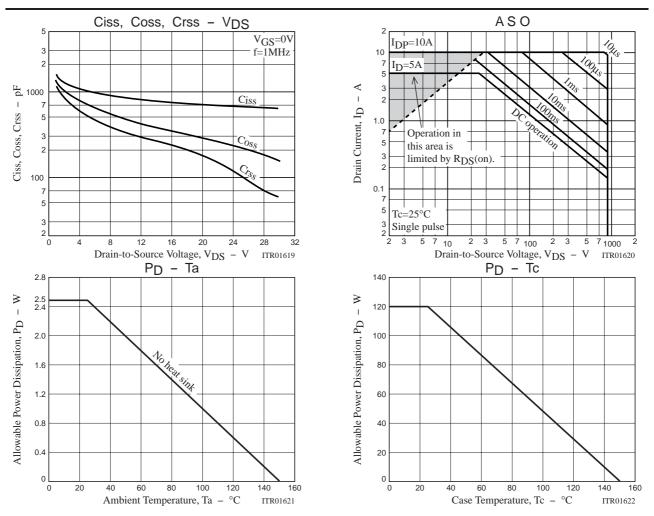


Switching Time Test Circuit









Note on usage : Since the 2SK1461 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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